Equipment Summary

- Furnaces
  - Dry, Wet Oxidation
  - LPCDV Nitride, Poly
  - Low Temperature Oxide
- Metal Film Deposition
  - Sputtering, Evaporation
- Photolithography
  - Contact Aligner, SEM/E-Beam
- Silicon Etching
  - Wet, XeF_2
- Plasma Asher, Isotropic Nitride Etch

Furnaces

Sputtering, Evaporation

Sputtering: Aluminum, Metals, RF - SiO_2

Evaporator: Chrome, Gold, Nickel, SiO

Michael Gaitan, NIST (http://mems.nist.gov)

Photolithography

UV Contact Aligner: 2 micrometer feature size.

Joel SEM: E-Beam photolithography sub 100nm features size over 1 cm area

Silicon Etching

Xenon Difloride Etcher

Wet Chemical Benches

Plasma Asher, Evaluation

Plasma Asher, Isotropic plasma etcher for nitride

NanoSpec, Ellipsometer